

MATERIAL DECLARATION SHEET



Material Number	P850-U180-WH			
Product Line	TBU			
Compliance Date	January-2008			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Semiconductor Device	Silicon Chip	7.84	Doped silicon	7440-21-3	100	5.53	5.53
2	Lead Frame	Copper alloy with silver plating	61.68	Copper	7440-50-8	95.645	41.61	43.5
				Iron	7439-89-6	2.185	0.95	
				Tin	7440-31-5	0.034	0.01	
				Zinc	7440-66-6	0.135	0.06	
				Silver (plating)	7440-22-4	2.0	0.87	
3	Bond wire	Gold wire	0.26	Gold	7440-57-5	100	0.18	0.18
4	Die Attach	Adhesive	2.56	Di-ester resin	proprietary	3	0.055	1.81
				Functionalized ester	proprietary	7	0.13	
				Polymeric compound	proprietary	3	0.055	
				Silver	7440-22-4	87	1.57	
5	Mold compound (halogen-free)	Epoxy resin	64.66	Silica fused	60676-86-0	90.5	41.27	45.6
				Epoxy resin	proprietary	4.7	2.14	
				Phenolic resin	proprietary	4.7	2.14	
				Carbon black	1333-86-4	0.1	0.05	
6	Matte tin plating	matte tin	4.79	Tin	7440-31-5	100	3.38	3.38
Total weight			141.79					

This Document was updated on: January 12, 2010

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.